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- Independent Registers for A and B Buses
- Multiplexed Real-Time and Stored Data
- Choice of True or Inverting Data Paths
- Choice of 3-State or Open-Collector Outputs
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (NT) and Ceramic (JT) 300-mil DIPs

DEVICE	OUTPUT	LOGIC
SN54ALS646, SN74ALS646A, 'AS646	3 state	True
SN54ALS648, SN74ALS648A, SN74AS648	3 state	Inverting

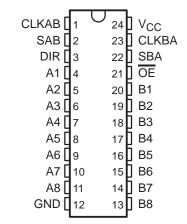
description

These devices consist of bus-transceiver circuits with 3-state or open-collector outputs, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the octal bus transceivers and registers.

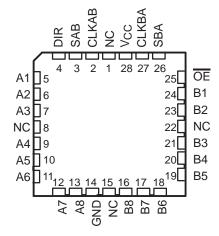
Output-enable (OE) and direction-control (DIR) inputs control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either or both registers.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode)

SN54ALS646, SN54ALS648, SN54AS646 . . . JT PACKAGE SN74ALS646A, SN74ALS648A, SN74AS646, SN74AS648 . . . DW OR NT PACKAGE (TOP VIEW)



SN54ALS646, SN54ALS648, SN54AS646 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. DIR determines which bus receives data when \overline{OE} is low. In the isolation mode (\overline{OE} high), A data may be stored in one register and/or B data may be stored in the other register.

When an output function is disabled, the input function is still enabled and can be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

The -1 version of the SN74ALS646A is identical to the standard version, except that the recommended maximum I_{OL} in the -1 version is increased to 48 mA. There are no -1 versions of the SN54ALS646, SN54ALS648A.

The SN54ALS646, SN54ALS648, and SN54AS646 are characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALS646A, SN74ALS648A, SN74AS646, and SN74AS648 are characterized for operation from 0°C to 70°C.



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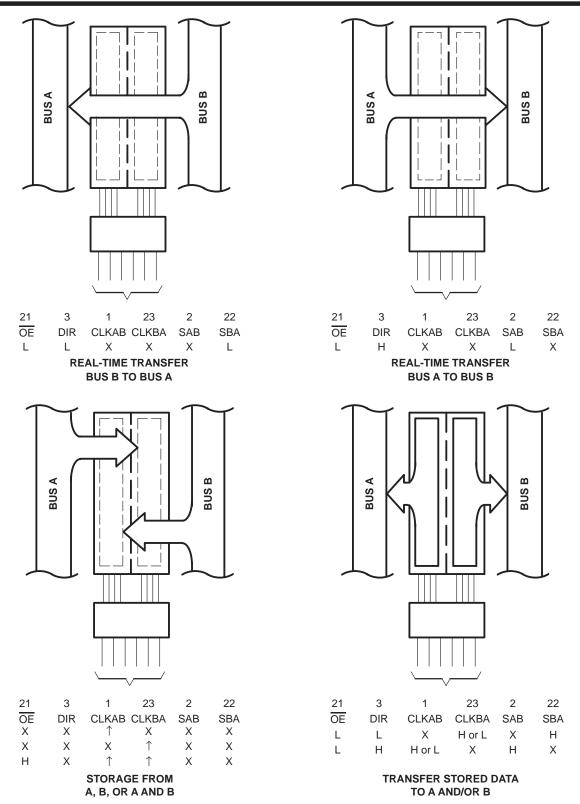


Figure 1. Bus-Management Functions

Pin numbers shown are for the DW, JT, and NT packages.



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Function Tables

SN54ALS646, SN54AS646, SN74ALS646A, SN74AS646

		INP	UTS			DAT	A I/O	OPERATION OR FUNCTION
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
Х	Х	1	Χ	Х	Χ	Input	Unspecified [†]	Store A, B unspecified [†]
Х	Χ	Χ	\uparrow	Χ	Χ	Unspecified [†]	Input	Store B, A unspecified [†]
Н	Х	1	↑	Х	Х	Input	Input	Store A and B data
Н	X	H or L	H or L	Χ	Χ	Input disabled	Input disabled	Isolation, hold storage
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Χ	Н	Output	Input	Stored B data to A bus
L	Н	Х	Χ	L	Χ	Input	Output	Real-time A data to B bus
L	Н	H or L	X	Н	Χ	Input	Output	Stored A data to B bus

[†] The data output functions can be enabled or disabled by various signals at $\overline{\text{OE}}$ and DIR. Data input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

SN54ALS648, SN74ALS648A, SN74AS648

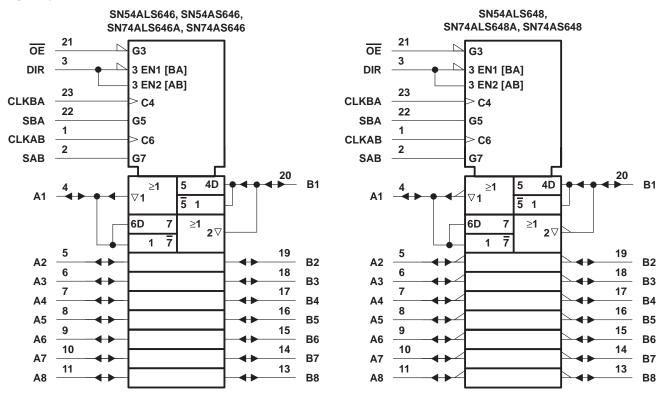
		INP	UTS			DAT	A I/O	OPERATION OR FUNCTION
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
Х	Х	1	Х	Х	Х	Input	Unspecified [†]	Store A, B unspecified [†]
Х	X	Χ	1	X	Χ	Unspecified [†]	Input	Store B, A unspecified [†]
Н	Х	1	1	Х	Χ	Input	Input	Store A and B data
Н	Х	H or L	H or L	Χ	Χ	Input disabled	Input disabled	Isolation, hold storage
L	L	Х	Χ	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Χ	Н	Output	Input	Stored \overline{B} data to A bus
L	Н	Х	Х	Ĺ	Х	Input	Output	Real-time \overline{A} data to B bus
L	Н	H or L	Χ	Н	Χ	Input	Output	Stored \overline{A} data to B bus

[†] The data output functions can be enabled or disabled by various signals at $\overline{\text{OE}}$ and DIR. Data input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



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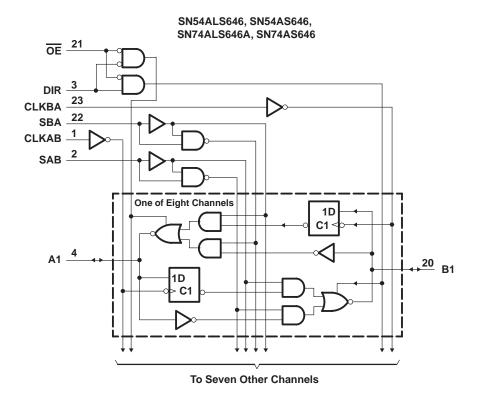
logic symbols†

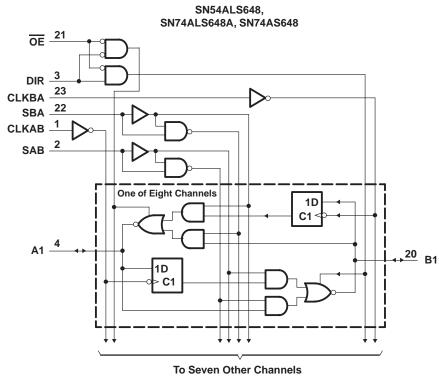


[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.



logic diagrams (positive logic)





Pin numbers shown are for the DW, JT, and NT packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}			. 7 V
Input voltage, V _I : Control inputs			. 7 V
I/O ports			5.5 V
Operating free-air temperature range, TA:	SN54ALS646	−55°C to	125°C
	SN74ALS646A	0°C to	70°C
Storage temperature range		−65°C to	150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	54ALS6	46	SN7	'4ALS64	6A	LINUT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vсс	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage	2			2			V	
\vee_{IL}	Low-level input voltage			0.7			0.8	V	
ЮН	High-level output current			-12			-15	mA	
	Low-level output current			12			24	4	
lOL							48‡	mA	
fclock	Clock frequency	0		35	0		40	MHz	
t _W	Pulse duration, CLKBA or CLKAB high or low	14.5			12.5			ns	
t _{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	15			10			ns	
t _h	Hold time, A after CLKAB↑ or B after CLKBA↑	0			0			ns	
TA	Operating free-air temperature	-55		125	0		70	°C	

[‡] Applies only to the -1 version and only if V_{CC} is maintained between 4.75 V and 5.25



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEST COL	IDITIONS	SN	54ALS6	46	SN7	4ALS64	6A	UNIT
'	PARAMETER	TEST CON	IDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNII
VIK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2			V _{CC} -2			
\/a			$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V
VOH			$I_{OH} = -12 \text{ mA}$	2						V
			$I_{OH} = -15 \text{ mA}$				2			
			I _{OL} = 12 mA		0.25	0.4		0.25	0.4	
VOL		-	I _{OL} = 24 mA					0.35	0.5	V
			$I_{OL} = 48 \text{ mA}^{\ddagger}$					0.35	0.5	
П	Control inputs	V00 = 5.5 V	V _I = 7 V			0.1			0.1	mA
''	A or B ports	V _{CC} = 5.5 V	V _I = 5.5 V			0.1			0.1	ША
	Control inputs	\/	V: 07V			20			20	^
ΊΗ	A or B ports§	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
	Control inputs	V 55V	V 0.4V			-0.2			-0.2	4
ΊL	A or B ports§	V _{CC} = 5.5 V,	$V_{I} = 0.4 V$			-0.2			-0.2	mA
IO¶		V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
			Outputs high		47	76		47	76	
ICC		<u> </u>	Outputs low		55	88		55	88	mA
			Outputs disabled		55	88		55	88	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

 $[\]ddagger$ Applies only to the -1 version and only if VCC is maintained between 4.75 V and 5.25 \$ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

¹ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

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switching characteristics (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C C _L R1 R2 T _A	UNIT			
			SN54A	LS646	SN74AL	S646A	
			MIN	MAX	MIN	MAX	
f _{max}			35		40		MHz
^t PLH	CLKBA or CLKAB	A or B	10	35	7	30	ns
^t PHL	CENDA OF CENAD	AOIB	5	20	5	17	115
^t PLH	A or B	B or A	5	22	3	20	ns
^t PHL		DUIA	3	15	3	12	113
^t PLH	SBA or SAB [‡] (stored data low)	A or B	10	40	7	35	ns
^t PHL		7 01 15	5	23	5	20	113
^t PLH	SBA or SAB‡	A or B	8	30	6	25	ns
^t PHL	(stored data high)	AOIB	5	24	5	20	ns
^t PZH	ŌĒ	A or B	3	20	2	17	ns
^t PZL	OE	AOIB	5	22	4	20	115
^t PHZ	ŌĒ	A or B	1	12	1	10	ns
^t PLZ	OE	AOIB	1	20	2	16	115
^t PZH	DIR	A or B	5	38	3	30	ns
t _{PZL}	DIK	AUIB	5	30	4	25	115
^t PHZ	DIR	A or B	1	12	1	10	ns
^t PLZ	אוט	AUIB	2	21	2	16	115

[†] For conditions shown MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}			. 7 V
Input voltage, V _I : Control inputs			. 7 V
I/O ports			5.5 V
Operating free-air temperature range, T _A :	SN54ALS648	-55°C to	125°C
	SN74ALS648A	0°C to	o 70°C
Storage temperature range		-65°C to	150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	54ALS6	SN74ALS648A			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
IOH	High-level output current			-12			-15	mA
loL	Low-level output current			12			24	mA
fclock	Clock frequency	0		35	0		40	MHz
t _W	Pulse duration, CLKBA or CLKAB high or low	14.5			12.5			ns
t _{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	15			10			ns
t _h	Hold time, A after CLKAB↑ or B after CLKBA↑	0			0			ns
TA	Operating free-air temperature	-55		125	0		70	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONS	SN	54ALS6	48	SN7	4ALS64	8A	UNIT
	PARAMETER	lesi co	NUTTIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNII
٧ıK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2			-1.2	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2			V _{CC} -2			
V/011			$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V
VOH		V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2						V
			$I_{OH} = -15 \text{ mA}$				2			
V		V _{CC} = 4.5 V	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
VOL		VCC = 4.5 V	I _{OL} = 24 mA					0.35	0.5	V
i.	Control inputs	V00 - 5 5 V	V _I = 7 V			0.1			0.1	mA
l _l	A or B ports	V _{CC} = 5.5 V	V _I = 5.5 V			0.1			0.1	
	Control inputs	V 55V	V 07V			20			20	^
ΊΗ	A or B ports‡	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
	Control inputs	V 55V)/ 0.4\/			-0.2			-0.2	^
lIL.	A or B ports‡	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.2			-0.2	mA
ΙΟ§		V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
			Outputs high		47	76		47	76	
Icc		V _{CC} = 5.5 V	Outputs low		57	88		57	88	mA
			Outputs disabled		57	88		57	88	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

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switching characteristics (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C C _L R1 R2 T _A	UNIT			
			SN54A	LS648	SN74AL	S648A	
			MIN	MAX	MIN	MAX	
f _{max}			35		40		MHz
^t PLH	CLKBA or CLKAB	A or B	8	39	7	33	ns
^t PHL	CENDA OF CENAD	AOID	5	23	5	20	113
^t PLH	A or B	B or A	3	20	2	17	ns
^t PHL		DOIN	2	12	2	10	113
^t PLH	SBA or SAB‡	A or B	5	44	5	39	ns
^t PHL	(stored data low)	7010	4	26	4	22	113
^t PLH	SBA or SAB‡	A or B	6	30	6	25	ns
^t PHL	(stored data high)	AOID	6	25	6	21	113
^t PZH	ŌĒ	A or B	4	25	2	22	ns
^t PZL	OE	AOID	4	25	4	22	113
^t PHZ	ŌĒ	A or B	1	12	1	10	ns
^t PLZ	OE .	7015	2	21	2	15	110
^t PZH	DIR	A or B	4	35	2	27	ns
^t PZL	DIIX	7015	3	25	3	19	110
^t PHZ	DIR	A or B	1	17	1	14	ns
t _{PLZ}	DIK	7016	2	22	2	15	115

[†] For conditions shown MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}			. 7 V
Input voltage, V _I : Control inputs			. 7 V
I/O ports			5.5 V
Operating free-air temperature range, TA:	: SN54AS646	−55°C to	125°C
	SN74AS646	0°C to	o 70°C
Storage temperature range		-65°C to	150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SI	N54AS64	16	SI	174AS64	6	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.8			0.8	V
loh	High-level output current				-12			-15	mA
loL	Low-level output current				32			48	mA
f _{clock} *	Clock frequency		0		75	0		90	MHz
4 *	Pulse duration	CLKBA or CLKAB high	6			5			ns
t _W *	ruise duration	CLKBA or CLKAB low	7			6			115
t _{su} *	Setup time, A before CLKAB↑ or B before	CLKBA [↑]	7			6			ns
t _h *	Hold time, A after CLKAB↑ or B before CL	KBA	0			0			ns
TA	Operating free-air temperature		-55		125	0		70	°C

^{*} On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TECT CO	NDITIONS	SN	54AS64	l6	SN	174AS64	6	LINUT
	PARAMETER	1551 CO	NDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
٧ıĸ		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2			V _{CC} -2			
\/a			$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V
VOH		$V_{CC} = 4.5 V$	$I_{OH} = -12 \text{ mA}$	2						V
			$I_{OH} = -15 \text{ mA}$				2			
\/0:		V _{CC} = 4.5 V	I _{OL} = 32 mA		0.25	0.5				V
VOL		VCC = 4.5 V	I _{OL} = 48 mA					0.35	0.5	V
ı	Control inputs	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
ΙΙ	A or B ports	V _{CC} = 5.5 V,	V _I = 5.5 V			0.1			0.1	IIIA
	Control inputs	\/ 55\/	V: 07V			20			20	^
ΊΗ	A or B ports‡	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			70			70	μΑ
	Control input	V 55V				-0.5			-0.5	
II∟	A or B ports‡	$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			-0.75			-0.75	mA
ΙΟ§		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
			Outputs high		120	195		120	195	
Icc		V _{CC} = 5.5 V	Outputs low		130	211		130	211	mA
			Outputs disabled		130	211		130	211	

 $[\]overline{\dagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

[‡] For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

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switching characteristics (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C C _L R1 R2 T _A	V,	UNIT		
			SN54A	\S646	SN74A		
			MIN	MAX	MIN	MAX	
f _{max} *			75		90		MHz
^t PLH	CLKBA or CLKAB	A or B	2	9.5	2	8.5	ns
^t PHL	CENDA OF CENAB	A 01 B	2	10	2	9	113
^t PLH	A or B	B or A	2	11.5	2	9	ns
^t PHL	AUD	DOLA	1	8	1	7	113
^t PLH	SBA or SAB‡	A or B	2	13.5	2	11	ns
^t PHL	SBA UI SAB+	7010	2	11	2	9	113
^t PZH	ŌĒ	A or B	2	11	2	9	ns
t _{PZL}	OE	AOID	3	15	3	14	113
^t PHZ	ŌĒ	A or B	2	11	2	9	ns
^t PLZ)E	7010	2	11	2	9	113
^t PZH	DIR	A or B	3	21	3	16	ns
^t PZL	DIIV	AUD	3	24	3	18	113
[†] PHZ	DIR	A or B	2	12	2	10	0 ns
t _{PLZ}	DIK	7016	2	12	2	10	115

^{*} On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

[†] For conditions shown MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}		7 V
Input voltage, V _I : Control inputs		7 V
I/O ports		5.5 V
Operating free-air temperature range, T _A : SN74AS648	. 0°C to	70°C
Storage temperature range	-65°C to 1	150°C

recommended operating conditions

			SI	174AS64	18	UNIT
			MIN	NOM	MAX	UNII
Vcc	Supply voltage		4.5	5	5.5	V
VIH	High-level input voltage		2			V
V _{IL}	Low-level input voltage				0.8	V
ІОН	High-level output current				-15	mA
lOL	Low-level output current				48	mA
fclock	Clock frequency		0		90	MHz
	Pulse duration	CLKBA or CLKAB high	5			no
t _W	Pulse duration	CLKBA or CLKAB low	6			ns
t _{su}	Setup time, A before CLKAB↑ or B before CLKBA↑		6			ns
th	Hold time, A after CLKAB↑ or B before CLKBA		0			ns
TA	Operating free-air temperature		0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEST COMP	NTIONS	SN	174AS64	18	LINUT
	PARAMETER	TEST COND	ITIONS	MIN	TYP‡	MAX	UNIT
٧ıK		$V_{CC} = 4.5 V,$	$I_{I} = -18 \text{ mA}$			-1.2	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2			
۷он		V 45V	IOH = -3 mA	2.4	3.2		V
		$V_{CC} = 4.5 \text{ V}$	$I_{OH} = -15 \text{ mA}$	2			
VOL		$V_{CC} = 4.5 V,$	I _{OL} = 48 mA		0.35	0.5	V
1.	Control inputs	Vac EEV	V _I = 7 V			0.1	A
'1	A or B ports	$V_{CC} = 5.5 \text{ V}$	V _I = 5.5 V			0.1	mA
	Control inputs		V 07V			20	
lін	A or B ports§	$V_{CC} = 5.5 V,$	V _I = 2.7 V			70	μΑ
	Control input					-0.5	
IIL	A or B ports§	$V_{CC} = 5.5 V,$	V _I = 0.4 V			-0.75	mA
Io¶		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	mA
			Outputs high		110	185	
Icc		$V_{CC} = 5.5 V$	Outputs low		120	195	mA
			Outputs disabled		120	195	

 $[\]ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

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switching characteristics (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 C _L = 50 pF R1 = 500 Ω R2 = 500 Ω T _A = MIN t	; , <u>2</u> , <u>2</u> ,	UNIT
			SN74	AS648	
			MIN	MAX	
f _{max}			90		MHz
^t PLH	CLKBA or CLKAB	A or B	2	8.5	ns
^t PHL	CENBA OF CENAB	AUB	2	9	115
^t PLH	A or B	B or A	2	8	ns
^t PHL	AUB	BULA	1	7	115
^t PLH	SBA or SAB‡	A or B	2	11	ns
^t PHL	SBA OF SAB+	AUB	2	9	115
^t PZH	ŌĒ	A or B	2	9	ns
^t PZL	OE OE	AUB	3	15	115
^t PHZ	ŌĒ	A or B	2	9	ns
t _{PLZ}	OE OE	AUB	2	9	115
^t PZH	DIR	A or B	3	16	ns
^t PZL	DIK	AOID	3	18	113
^t PHZ	DIR	A or B	2	10	ns
t _{PLZ}	DIK	A 01 B	2	10	115

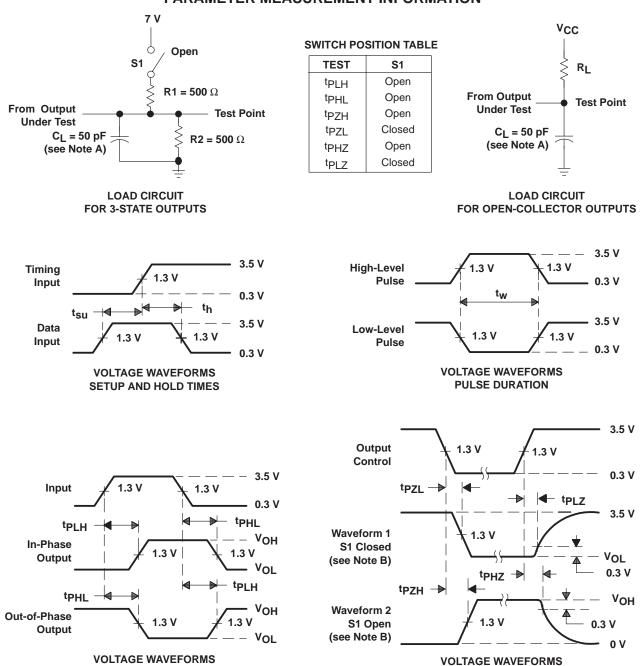
[†] For conditions shown MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

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ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

PROPAGATION DELAY TIMES

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuits and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87595013A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 87595013A SNJ54AS 646FK	Samples
5962-8759501KA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8759501KA SNJ54AS646W	Samples
5962-8759501LA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8759501LA SNJ54AS646JT	Samples
5962-89956013A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 89956013A SNJ54ALS 646FK	Samples
5962-8995601LA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8995601LA SNJ54ALS646JT	Samples
5962-9052301LA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9052301LA SNJ54ALS648JT	Sample
SN54AS646JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS646JT	Sample
SN74ALS646A-1DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS646A-1	Sample
SN74ALS646A-1DWR	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70	ALS646A-1	
SN74ALS646A-1DWRE4	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74ALS646A-1DWRG4	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74ALS646A-1NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	74ALS646A-1NT	Sample
SN74ALS646A-1NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	74ALS646A-1NT	Sample
SN74ALS646ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS646A	Sample
SN74ALS646ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS646A	Sample
SN74ALS646ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS646A	Samples
SN74ALS646ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS646ANT	Samples



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Orderable Device	Status	Package Type		Pins			Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74ALS648ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS648A	Sample
SN74ALS648ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS648ANT	Sample
SN74AS646DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS646	Sample
SN74AS646NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS646NT	Sample
SN74AS646NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS646NT	Sample
SN74AS648NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS648NT	Sample
SN74AS648NT3	OBSOLETI	E PDIP	NT	24		TBD	Call TI	Call TI	0 to 70		
SNJ54ALS646FK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 89956013A SNJ54ALS 646FK	Sample
SNJ54ALS646JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8995601LA SNJ54ALS646JT	Sample
SNJ54ALS646W	OBSOLETI	E CFP	W	24		TBD	Call TI	Call TI	-55 to 125		
SNJ54ALS648FK	OBSOLETI	E LCCC	FK	24		TBD	Call TI	Call TI	-55 to 125		
SNJ54ALS648JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9052301LA SNJ54ALS648JT	Sample
SNJ54ALS648W	OBSOLETI	E CFP	W	24		TBD	Call TI	Call TI	-55 to 125		
SNJ54AS646FK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 87595013A SNJ54AS 646FK	Sampl
SNJ54AS646JT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8759501LA SNJ54AS646JT	Sampl
SNJ54AS646W	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8759501KA SNJ54AS646W	Sampl

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PACKAGE OPTION ADDENDUM



n 10-Jun-2014

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS646, SN54ALS648, SN54AS646, SN74AS646:

Catalog: SN74ALS646, SN74ALS648, SN74AS646

Military: SN54AS646

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product



PACKAGE OPTION ADDENDUM



10-Jun-2014

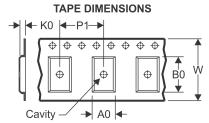
• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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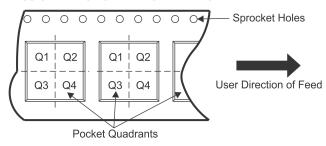
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

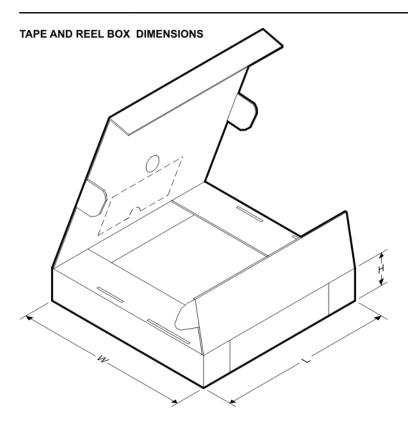
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS646ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

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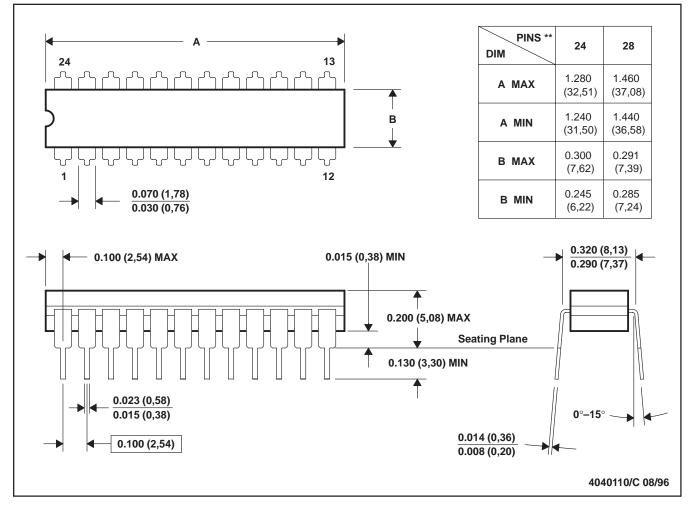
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS646ADWR	SOIC	DW	24	2000	367.0	367.0	45.0

JT (R-GDIP-T**)

24 LEADS SHOWN

CERAMIC DUAL-IN-LINE

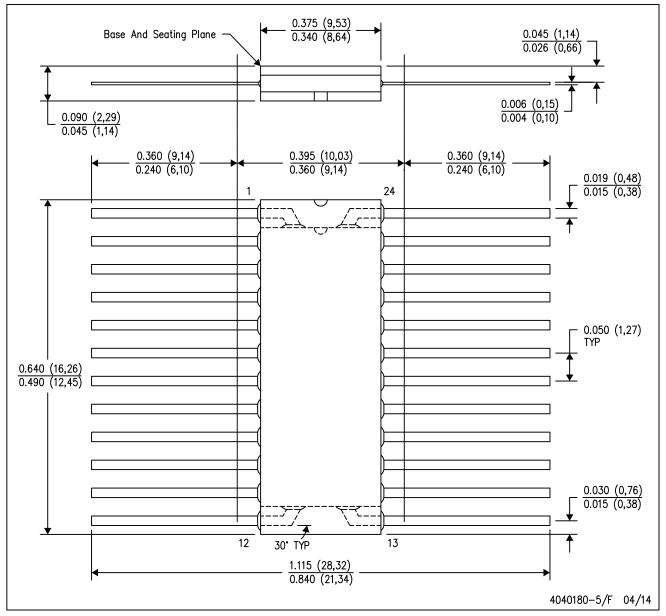


NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

W (R-GDFP-F24)

CERAMIC DUAL FLATPACK



NOTES:

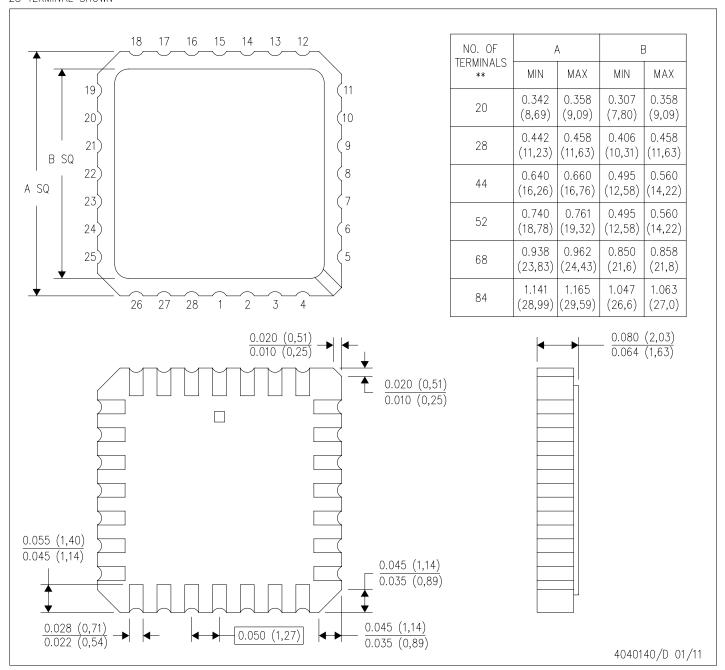
- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only. E. Falls within Mil—Std 1835 GDFP2—F20



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES:

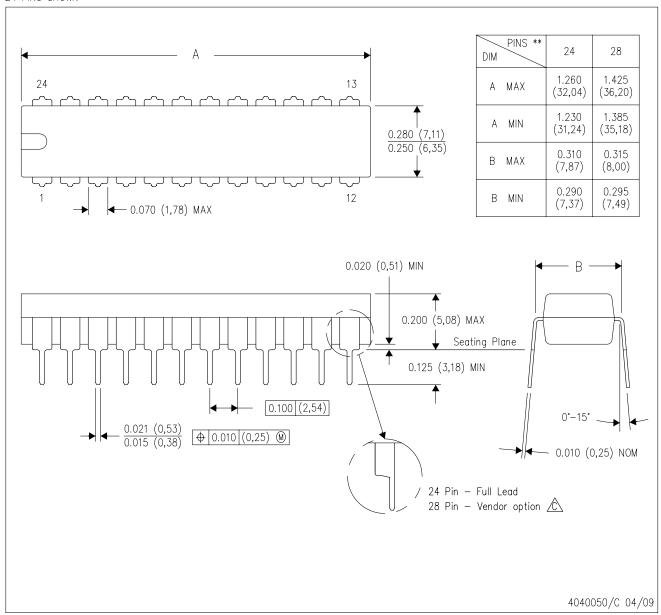
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

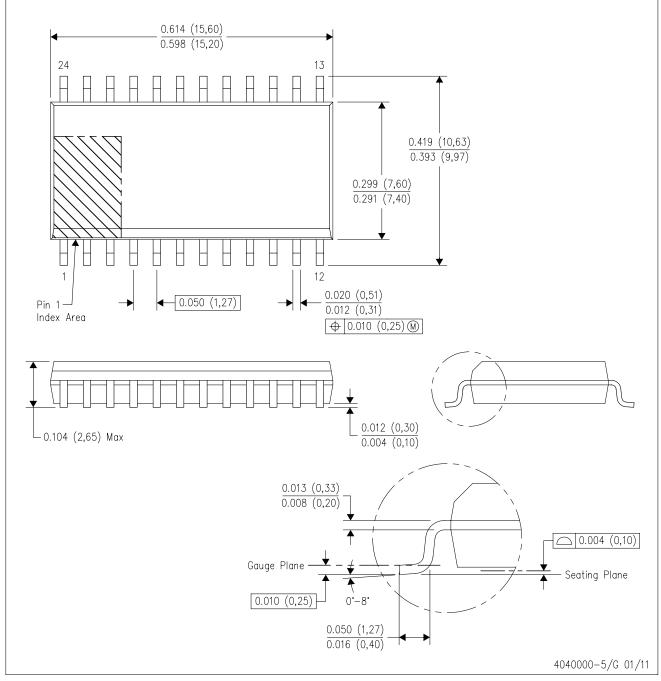
B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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